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2.9.4 Synergies of Operational Stress Factors 2.9.5 Synergetic Team;  
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during Fabrication Preparation; 3.2.1 Reliability Analysis of Materials;  
3.2.2 Degradation Phenomena in Polymers used in Electron  
Components; 3.3 FA during Fabrication; 3.3.1 Manufacturing History;  
3.3.2 Reliability Monitoring; 3.3.3 Wafer-Level Reliability  
3.3.4 Yield and Reliability 3.3.5 Packaging Reliability; 3.3.6 Improving  
Batch Reliability: Screening and Burn-In; 3.4 FA after Fabrication; 3.4.1  
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## Sommario/riassunto

Failure analysis is the preferred method to investigate product or process reliability and to ensure optimum performance of electrical components and systems. The physics-of-failure approach is the only internationally accepted solution for continuously improving the reliability of materials, devices and processes. The models have been developed from the physical and chemical phenomena that are responsible for degradation or failure of electronic components and materials and now replace popular distribution models for failure mechanisms such as Weibull or lognormal. Reliability engineers need

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